Plaskon 3400F-14

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is a fast curing, reduced-stress epoxy molding compound for the encapsulation of semiconductor devices including DIPs, PLCCs, SOICs and medium lead count QFPs. It was developed with fine filler particles especially for use with automated or conventional molding equipment and offers a balance of end use properties.

General Information			
Features	Semi-conductive		
	Laser marking		
	Fast molding cycle		
	Fast curing		
	Good formability		
	Excellent appearance		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.80	g/cm³	ASTM D792
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus	1.52	MPa	ASTM D790
Flexural Strength	0.0124	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	150	°C	ASTM E1356
CLTE - Flow	2.1E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	16	W/m/K	ASTM C177
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	1.6E+16	ohms·cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.80		ASTM D150
Dissipation Factor (1 kHz)	2.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	32	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: 5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 177°C, 1000 psi: 54 to 78 cmAutomatic Orifice Viscosity, 175°C, 1000 psi, 1 mm die length, 1/2 mm diameter: 10 to 16 Pascal secRam Follower Gel Time, 177°C: 8 secAsh Content: 71.4 %Hydrolyzable Halides: <10 ppmCull Hot Hardness, Shore D, 90 sec, 175°C: 70Arc Resistance, 110v AC180 secAll test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 21 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 60 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding:
Molding Temperature: 170 to 185°C
Molding Pressure: 750 to 1000 psi
Cure Time, 177°C: 20 to 26min
Post Mold Cure Time, 175°C: 4 to 12 hr

Recommended distributors for this material

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